

HSM221C

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0552-0500 (Previous: ADE-208-028D) Rev.5.00 Mar 10, 2005

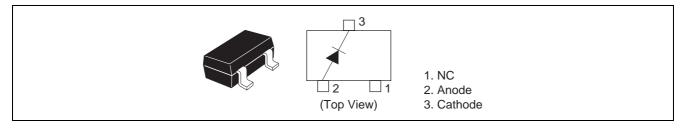
Features

- Low capacitance, proof against high voltage.
- Fast recovery time.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSM221C	A2	MPAK	PLSP0003ZC-A (MPAK)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	85	V
Reverse voltage	V _R	80	V
Peak forward current	I _{FM}	300	mA
Non-Repetitive peak forward surge current	I _{FSM} * ¹	4	А
Average rectified current	lo	100	mA
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	٥°

Note: 1. Value at duration of 1 $\mu s.$

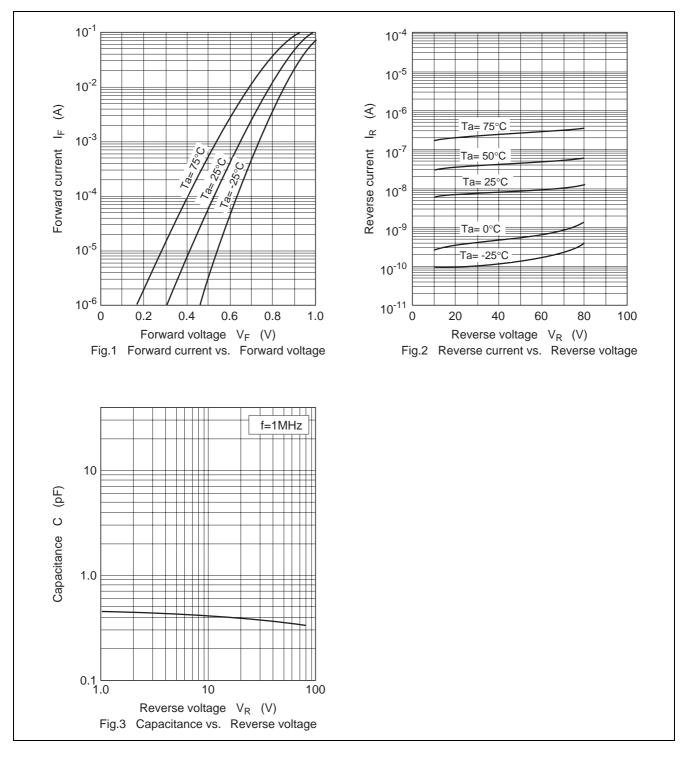
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

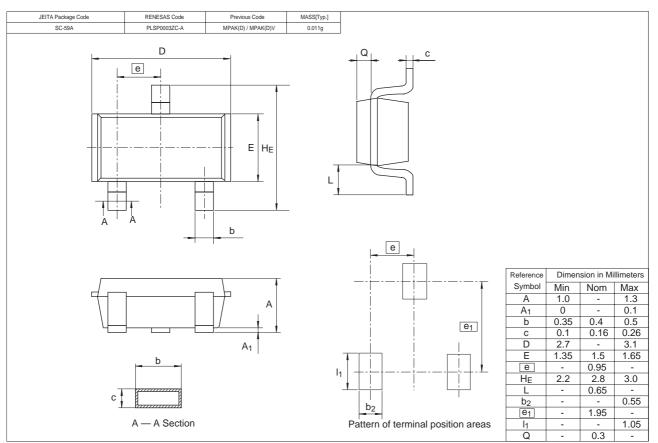
ltem	Symbol	Min	Тур	Мах	Unit	Test Condition
Forward voltage	V _{F1}	_	0.76	1.0	V	I _F = 10 mA
	V _{F2}	_	0.88	1.0		I _F = 50 mA
	V _{F3}	_	0.97	1.2		I _F = 100 mA
Reverse current	I _R	_	—	0.1	μA	V _R = 80 V
Capacitance	С	_	0.5	2.0	pF	V _R = 0 V, f = 1 MHz
Reverse recovery time	t _{rr}	_	—	3.0	ns	I_F = 10 mA, V_R = 6 V, R_L = 50 Ω



Main Characteristic



Package Dimensions





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